ATTY. DOCKET NO.
APPLICATION NO.
10/628,217

APPLICANT
Pornarede, et al.

FILING DATE
July 24, 2003

ATTY. DOCKET NO.
APPLICATION NO.
10/628,217

APPLICANT
Pornarede, et al.

GROUP
Unknown

U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
CK	1	2,394,930	2/12/46	McRae			
OX	2	3,895,127	7/15/75	Comizzoli			
$\mathcal{C}X$	3	4,056,642	11/1/77	Saxena et al.			
OX	4	4,292,343	9/29/81	Plaettner et ai.			
OX.	5	4,343,830	8/10/82	Sarma et al.			
\mathbb{O}	6	4,436,761	3/13/84	Hayashi et al.			
·CX	7	4,544,571	10/1/85	Miller			
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	20	6,200,866	03/13/01	Ma et al. ?: }/			

	FOREIGN PATENT DOCUMENTS							
EXAMINER		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
INITIAL			}				· YES	NO
(1)8.	21	JP 60 254621 A	16.12.85	Patent Abstracts of Japan				
OX.	22	JP 2000 160342 A	13.10.00	Patent Abstracts of Japan				
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EXAMINER (/	huster	Yoracele	DATE CONSIDERED	6,	126	104	
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		SHEET 2 OF	: 2
U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY, DOCKET NO. ASMEX.284DV1	APPLICATION NO. 10/626,217	
ISCLOSURE STATEMENT			_
APPLICANT	APPLICANT Pomarede, et al.		
SHEETS IF NECESSARY)	FILING DATE July 24, 2003	GROUP Unknown	
	July 27, 2000		

EXAMINER	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)
INITIAL	 Kim, H. and R. Reif, <i>Thin Solid Films</i>, Vol. 289:192-198 (1996), "In-situ low-temperature (600°C) wafer surface cleaning by electron cyclotron resonance hydrogen plasma" Ramm J. and E. Beck, <i>Thin Solid Films</i>, Vol. 246:158-163 (1994), "Low temperature epitaxial growth by molecular beam epitaxy on hydrogen-plasma-cleaned silicon wafers."

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FORM PTO-1449

INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

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